IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.:

09/627,979

Examiner:

DiLinh Nguyen

Inventor:

Randy H. Y. Lo, Chi-Chuan Wu and Ssu-Cheng Lai

Art Unit:

2814

Filed: Title:

June 24, 2000 Method Of Packaging Multi Chip Module

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Box Non-Fee Amendment, Commissioner for Patents, Washington, D.C. 20231, on the date shown below.

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Honorable Commissioner for Patents

Washington, D.C. 20231

RESPONSE TO ELECTION/RESTRICTION REQUIREMENT

Sir:

AMENDMENT

CLAIMS:

Please cancel claims 27-40.

REMARKS

In response to the election/restriction requirement in the Office Action dated 09/05/2001, applicants elect claims 1-26 drawn to a semiconductor device of the invention to prosecute without traverse.

Respectfully submitted,

Jason Z. Lin

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